

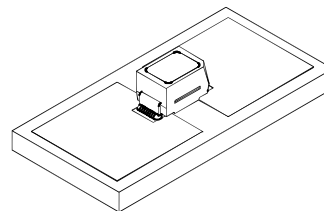
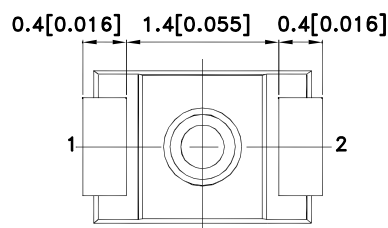
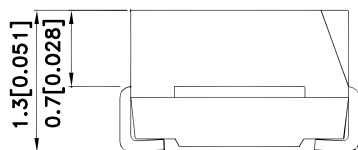
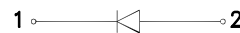
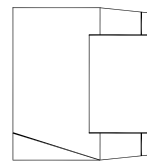
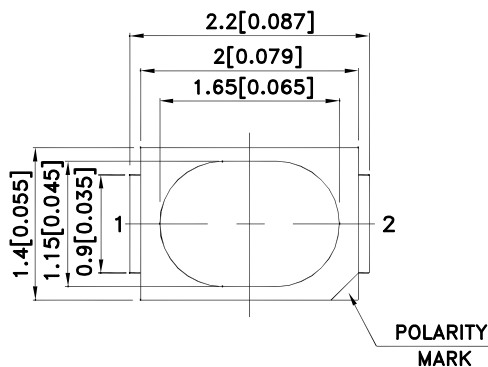
Features

- 2.2mm x 1.4mm, 1.3mm high.
- Low power consumption.
- Available on tape and reel.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.008") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

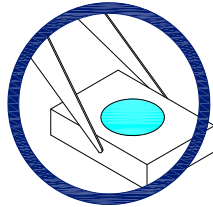


Handling Precautions

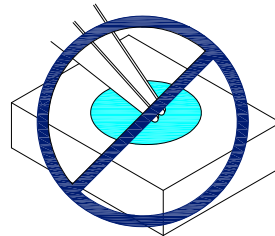
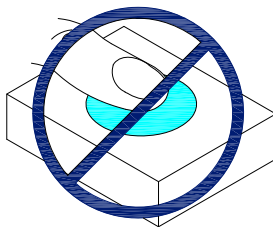
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

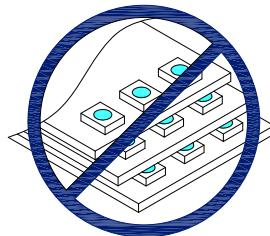
1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



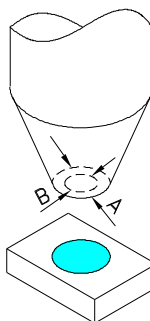
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AA2214SES/J4	Super Bright Orange (AlGaInP)	Water Clear	1800	2700	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	IF=20mA
C	Capacitance	Super Bright Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

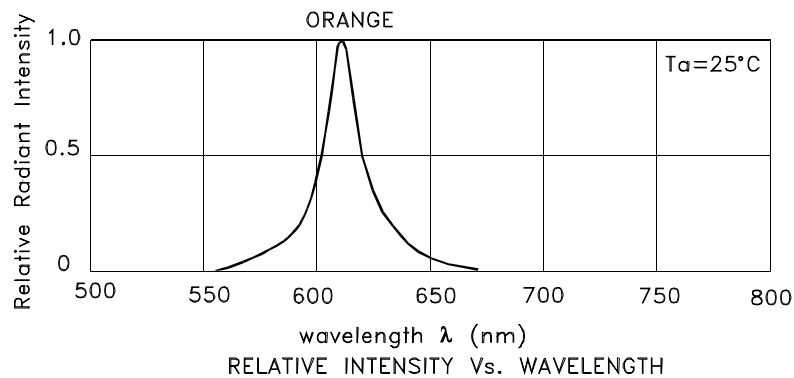
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

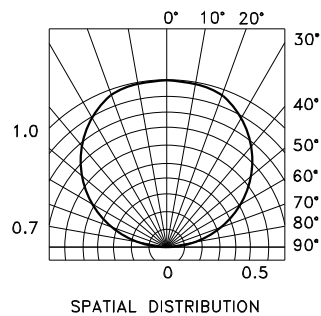
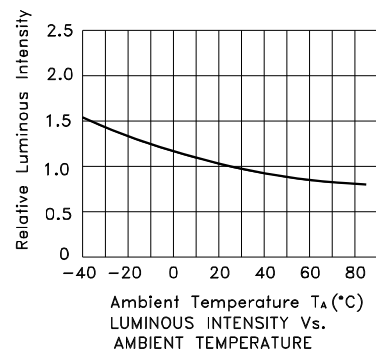
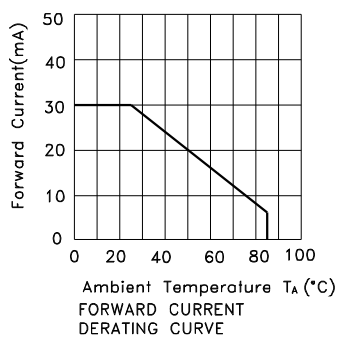
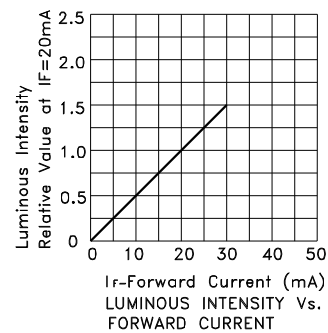
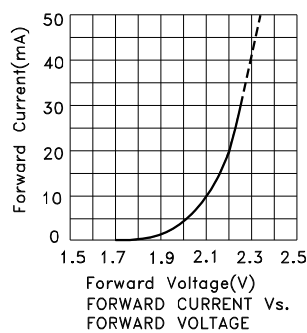
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

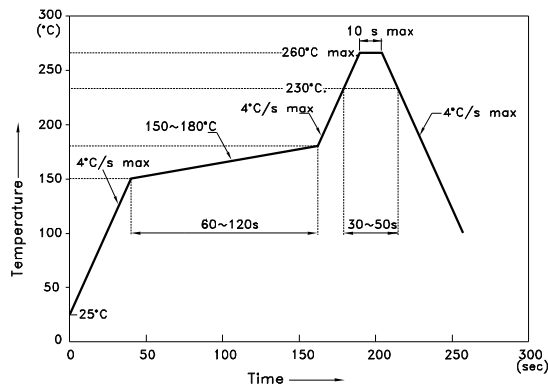
AA2214SES/J4



AA2214SES/J4

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

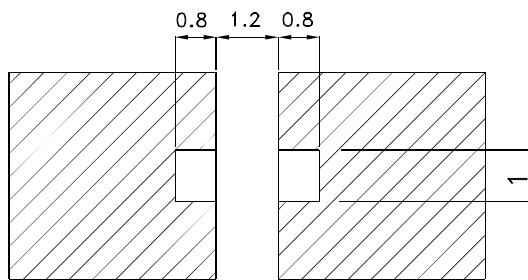
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

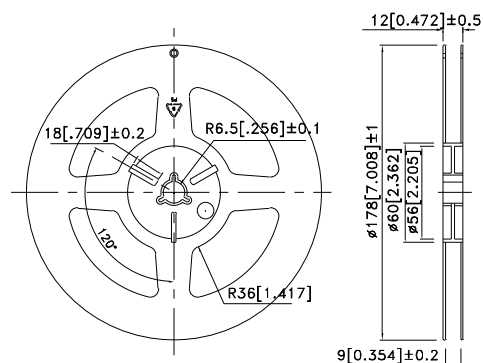
1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

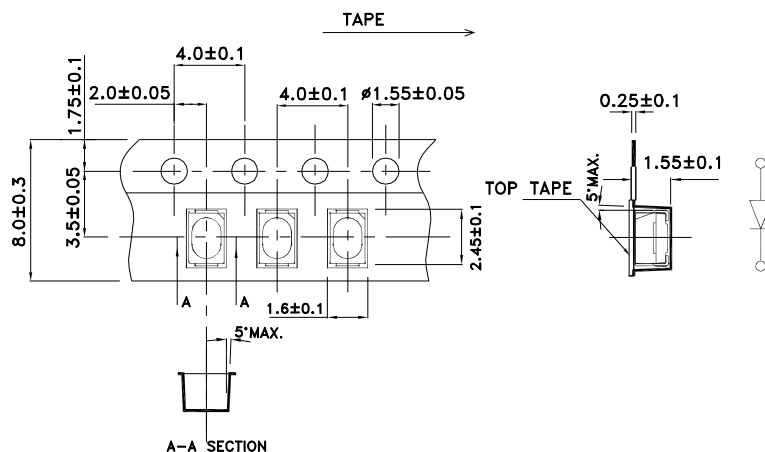


Solder Resist

Reel Dimension

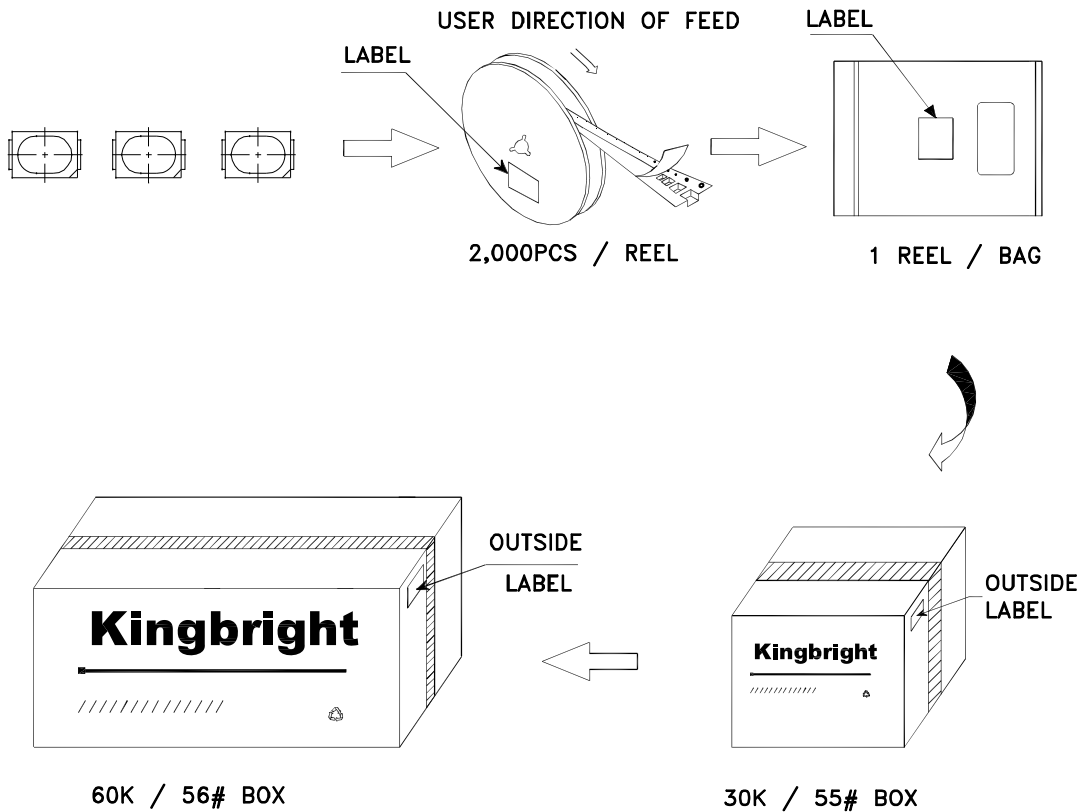



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

AA2214SES/J4



Kingbright	
P/NO: AA2214xxx	
QTY: 2,000 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	

Part Number: AA3021SES/J4

Super Bright Orange

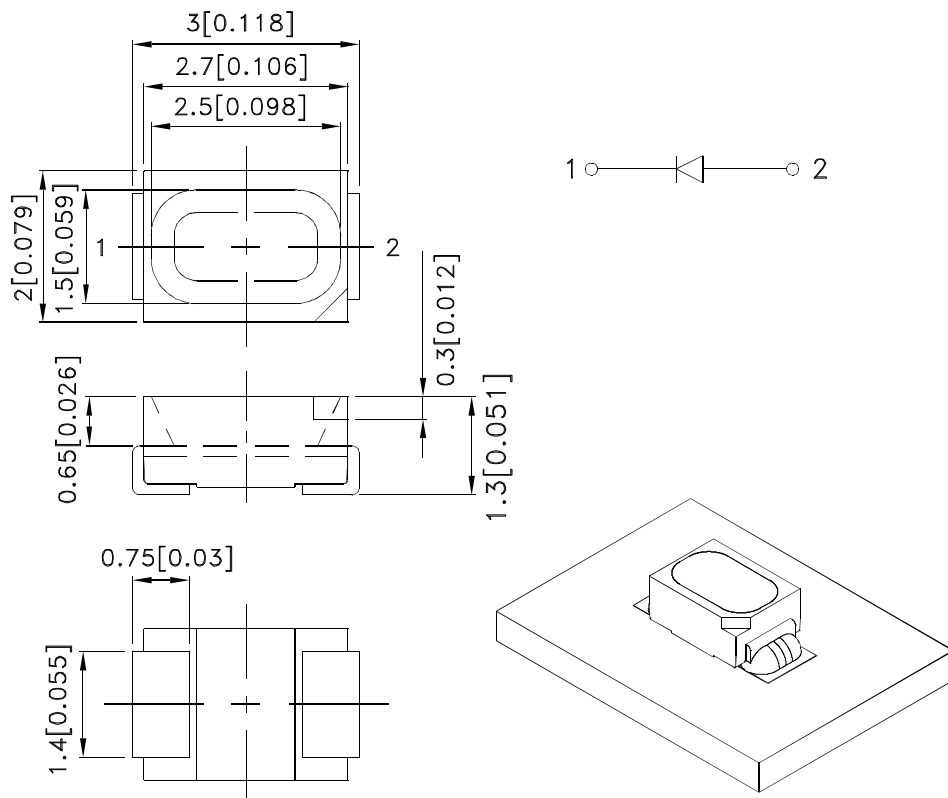
Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.008") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

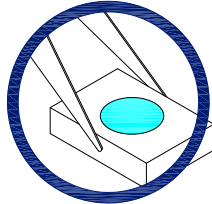


Handling Precautions

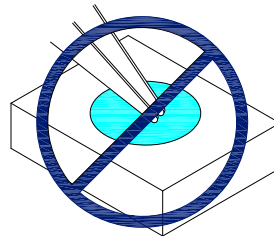
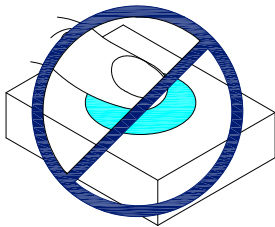
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

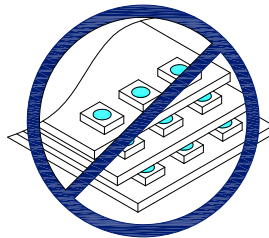
1. Handle the component along the side surfaces by using forceps or appropriate tools.



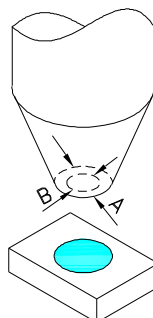
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AA3021SES/J4	Super Bright Orange (AlGaInP)	Water Clear	2200	2800	125°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	IF=20mA
C	Capacitance	Super Bright Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

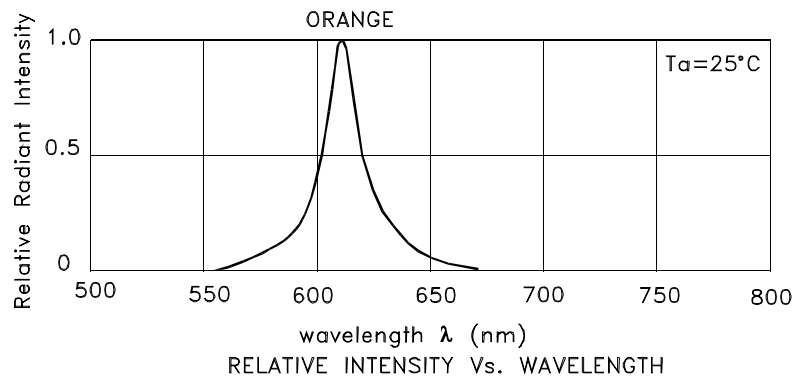
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

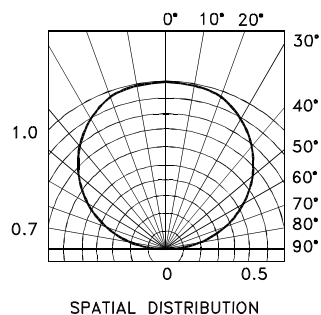
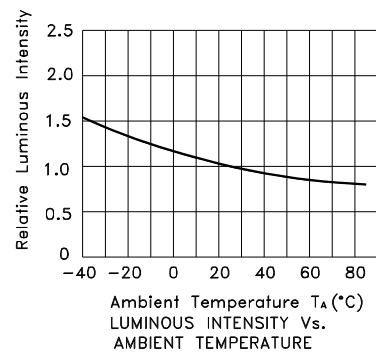
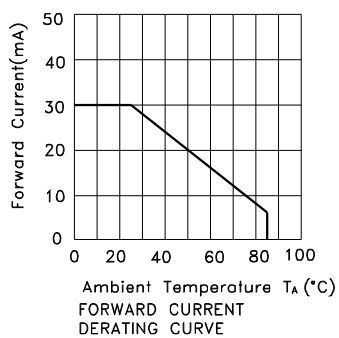
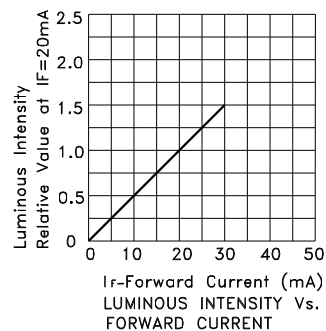
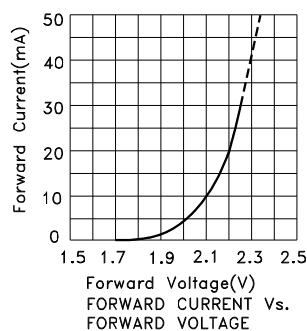
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

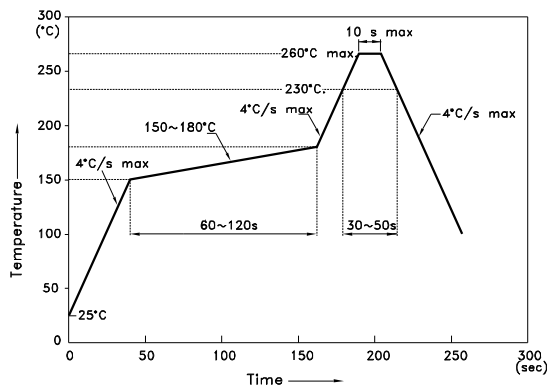
AA3021SES/J4



AA3021SES/J4

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

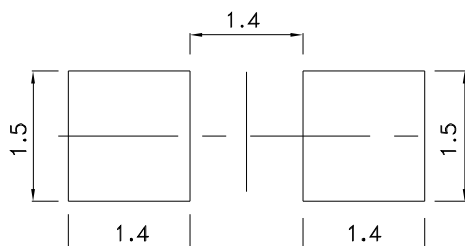
Reflow Soldering Profile For Lead-free SMT Process.



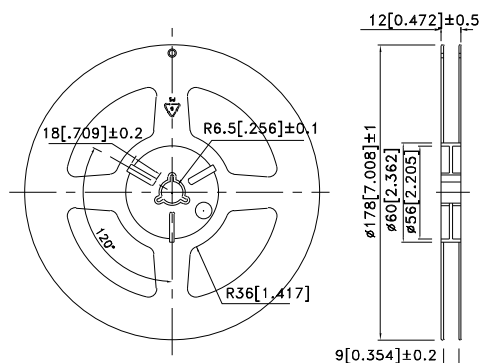
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

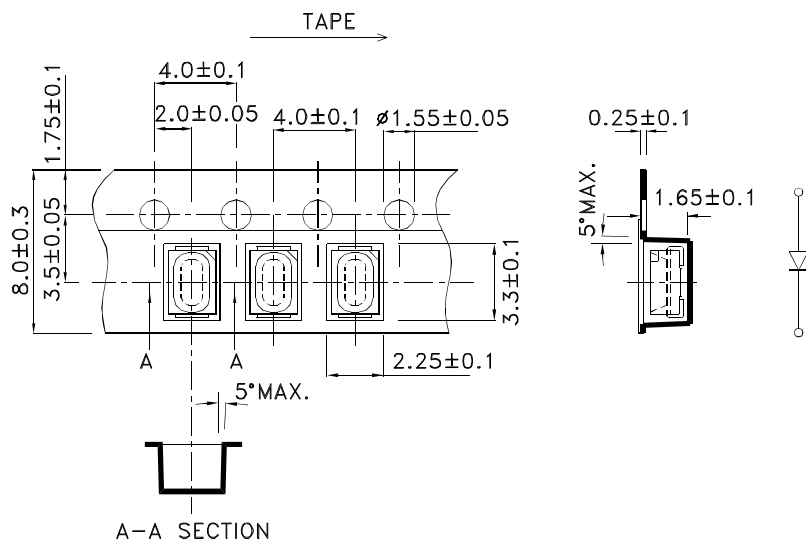
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

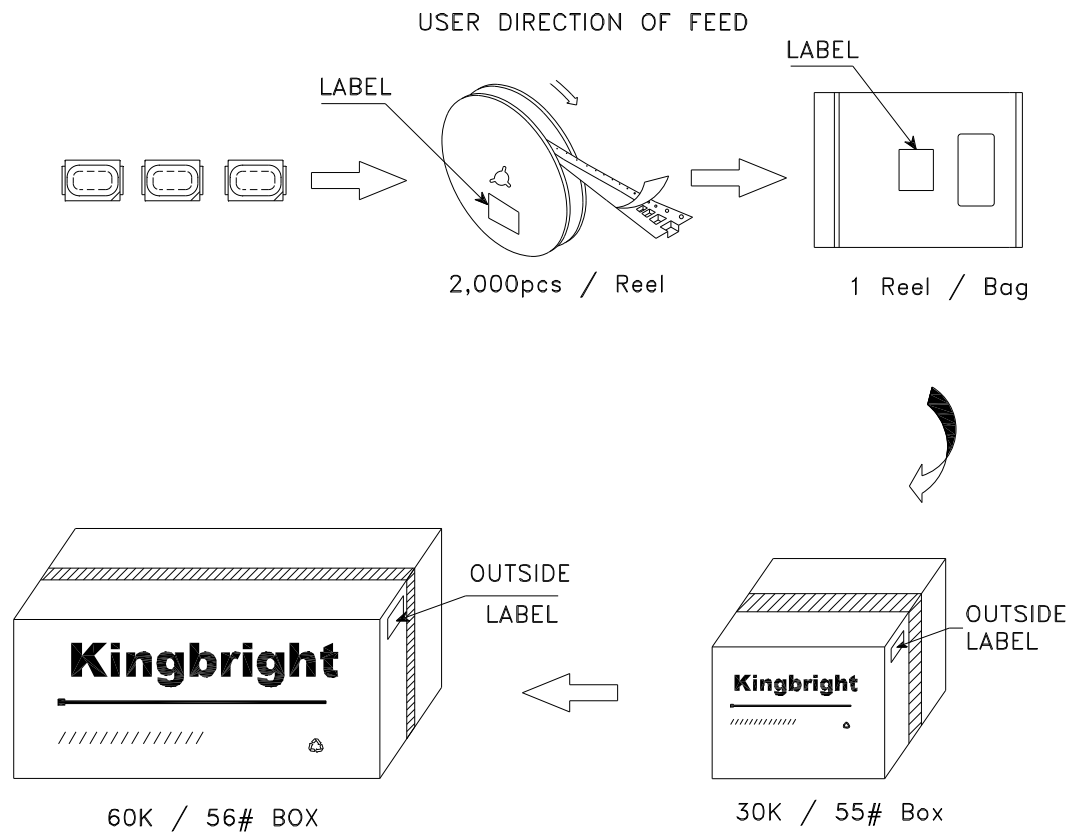



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

AA3021SES/J4



Kingbright	
P/NO: AA3021xxx	
QTY: 2,000 pcs	Q.C. <div>Q C xx xx xxxx PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	

Part Number: AA3528SES/J4

Super Bright Orange

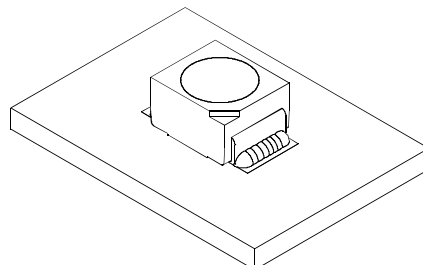
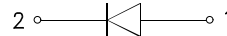
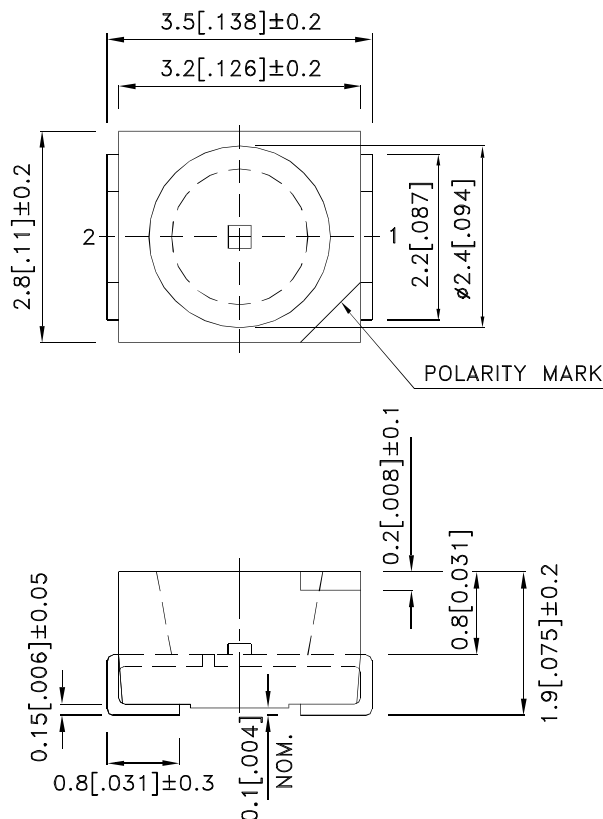
Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

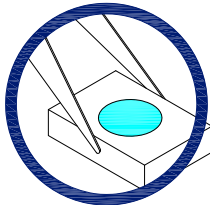


Handling Precautions

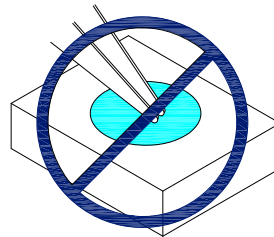
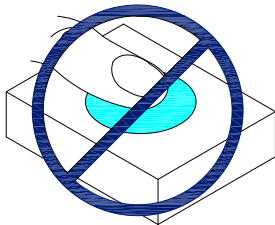
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

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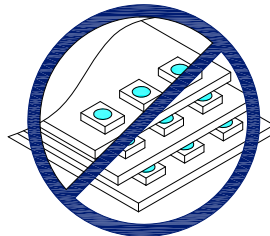
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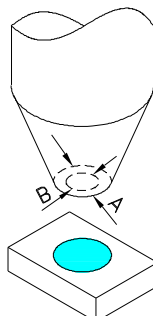
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LED. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AA3528SES/J4	Super Bright Orange (AlGaInP)	Water Clear	2300	2800	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	IF=20mA
C	Capacitance	Super Bright Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

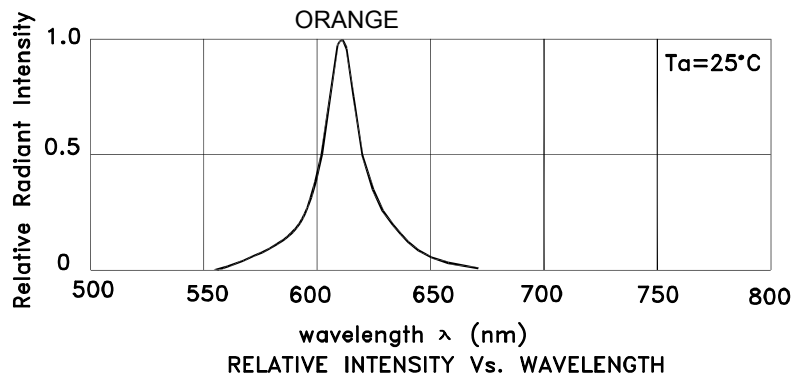
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	140	mW
DC Forward Current	50	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

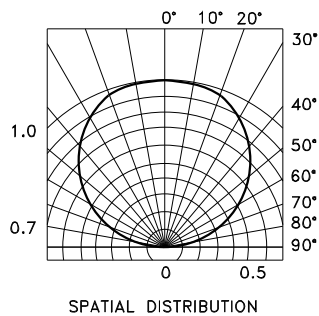
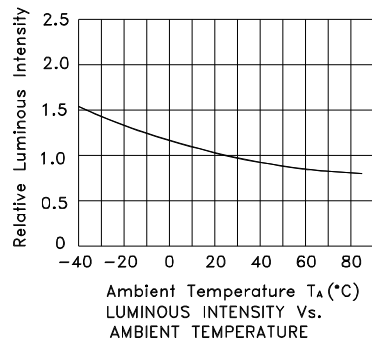
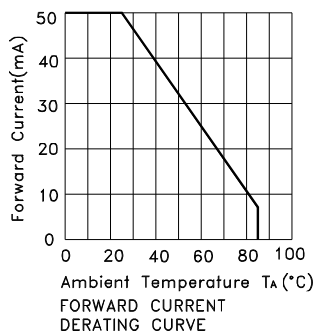
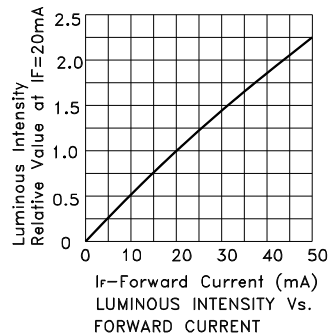
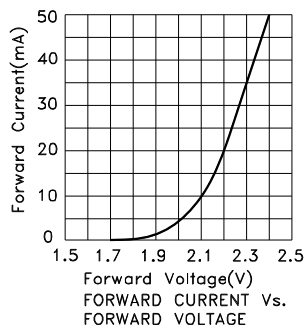
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

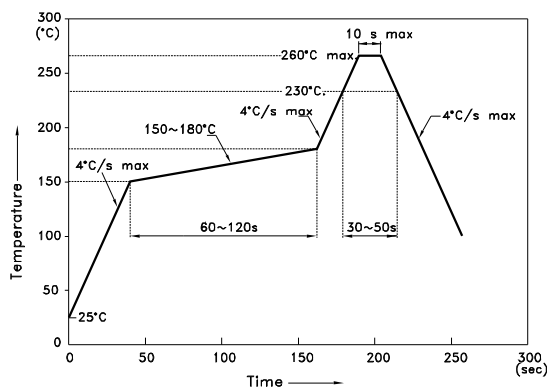
AA3528SES/J4



AA3528SES/J4

Reflow soldering is recommended and the soldering profile is shown below.
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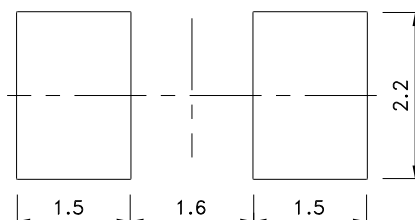
Reflow Soldering Profile For Lead-free SMT Process.



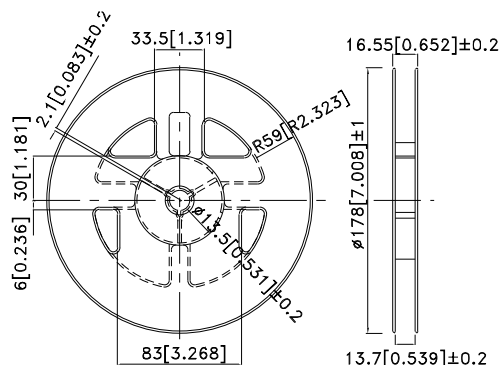
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

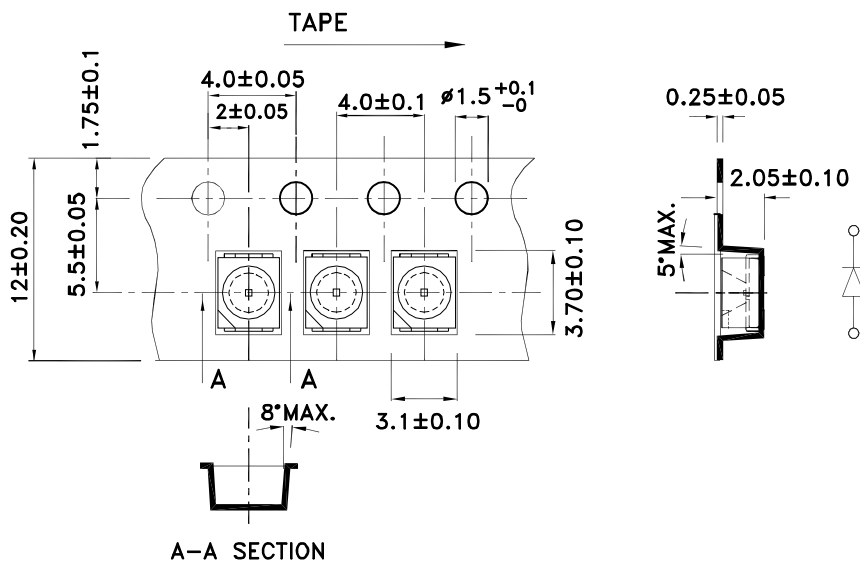
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)




Reel Dimension



Tape Dimensions (Units : mm)



<h1>Kingbright</h1>		
P/N: AA3528xxx		
QTY: 1,500 pcs	Q.C.	<div>Q C xx xx xxxx PASSED</div>
S/N: XXXX		
CODE: XXX		
LOT NO:		
 xxxxxxxxxxxxxxxxxxxxxxxx		
RoHS Compliant		

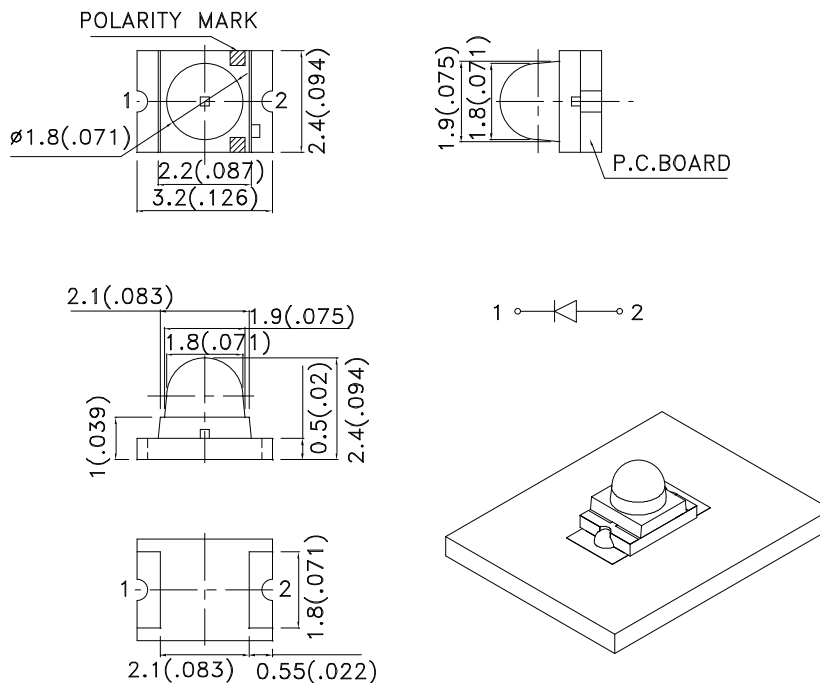
Features

- 3.2x2.4mm SMT LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.1(0.004)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APD3224SEC/J4	Super Bright Orange (AlGaInP)	Water Clear	9000	14000	20°
			*2300	*4000	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ Luminous Flux: +/-15%.
- * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	I _F =20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	I _F =20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	I _F =20mA
C	Capacitance	Super Bright Orange	27		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R = 5V

Notes:

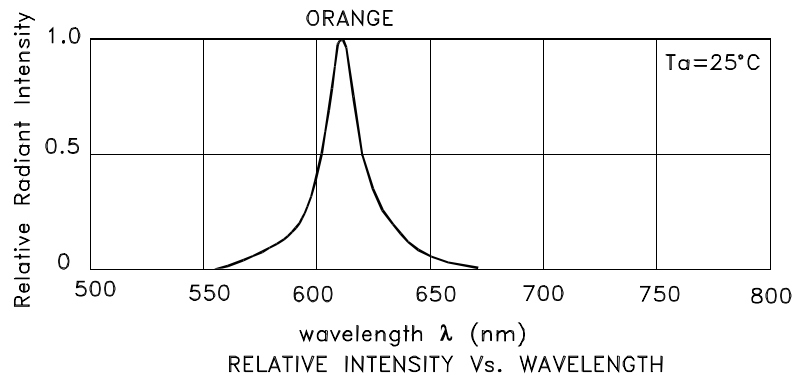
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

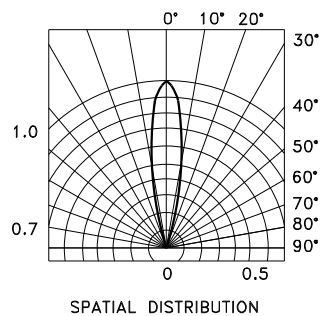
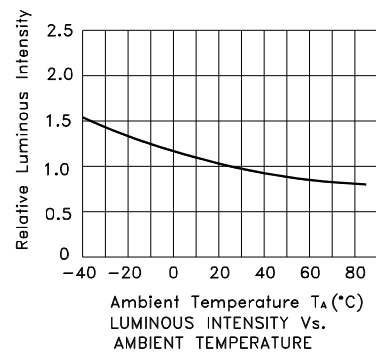
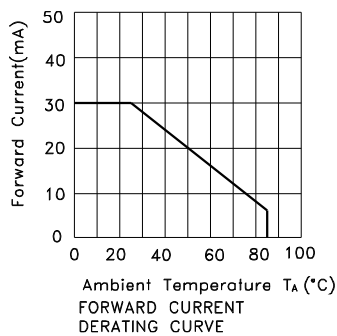
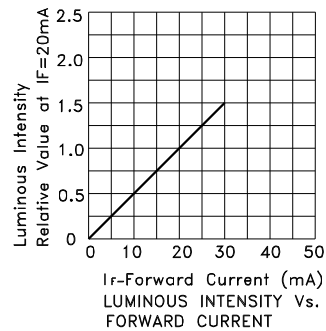
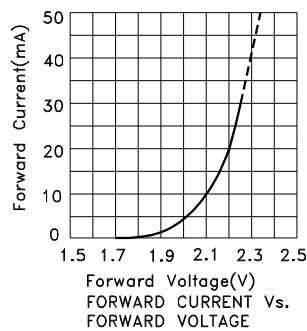
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

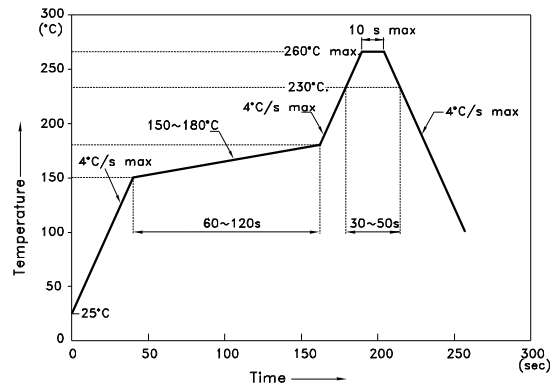
APD3224SEC/J4



APD3224SEC/J4

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

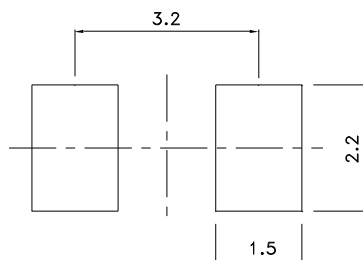
Reflow Soldering Profile For Lead-free SMT Process.



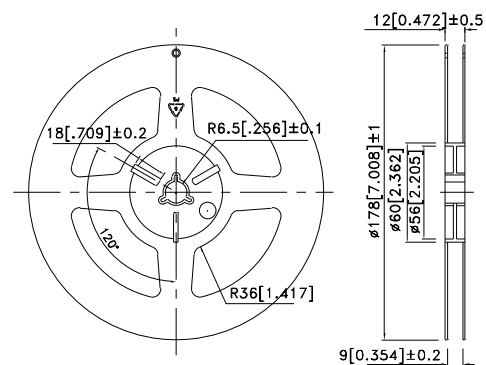
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

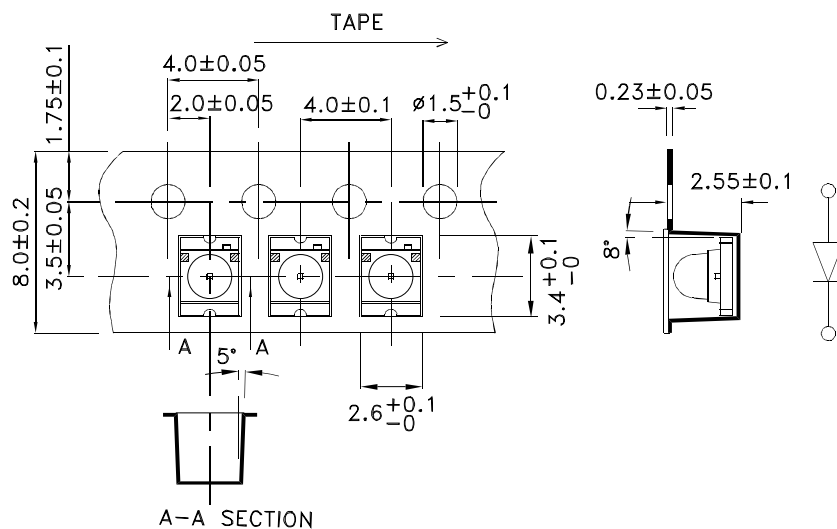
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

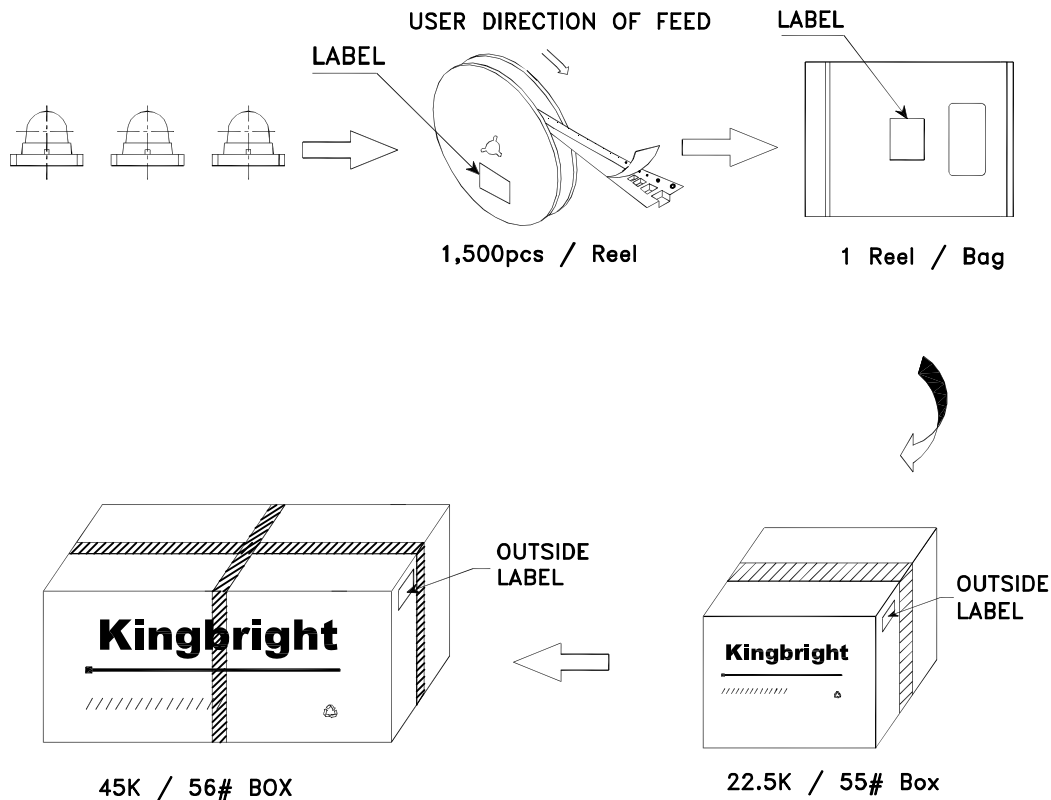



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

APD3224SEC/J4



Kingbright	
P/NO: APD3224xxx	
QTY: 1,500 pcs	Q.C. <div>Q C XX XX XXXX PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	

Part Number: APT1608SEC/J4-PRV

Super Bright Orange

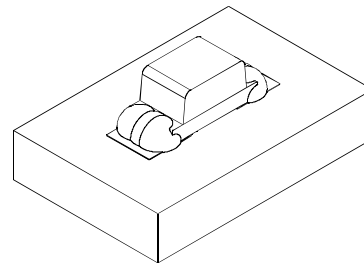
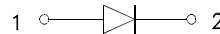
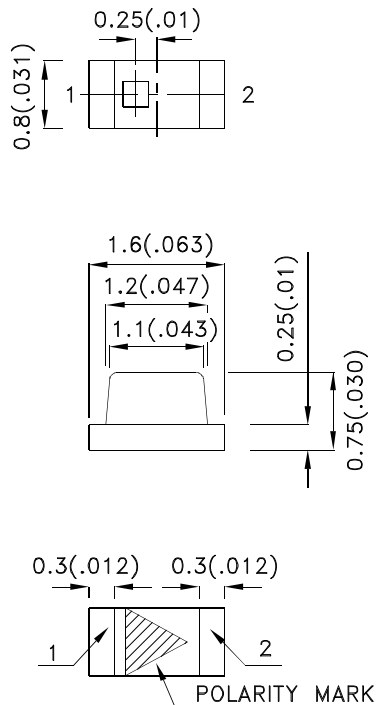
Features

- 1.6mmX0.8mm SMT LED, 0.75mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.1(0.004)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APT1608SEC/J4-PRV	Super Bright Orange (AlGaInP)	Water Clear	1600	2300	120°

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	611		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	605		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	17		nm	I _F =20mA
C	Capacitance	Super Bright Orange	27		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

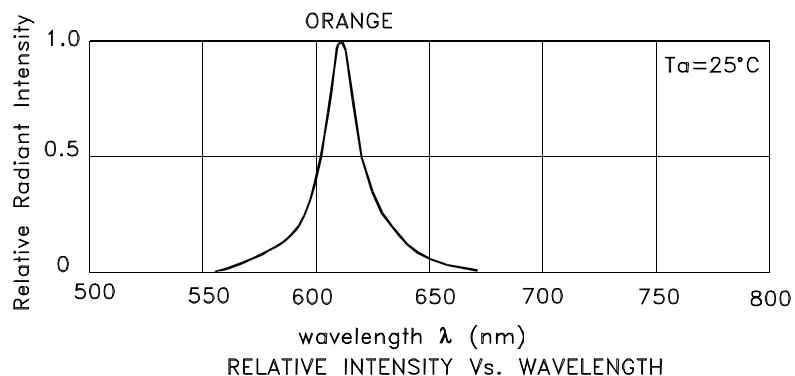
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

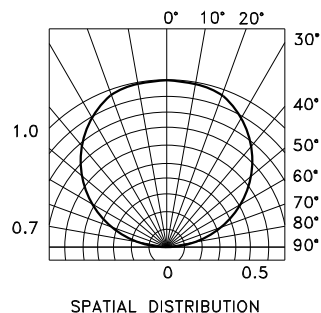
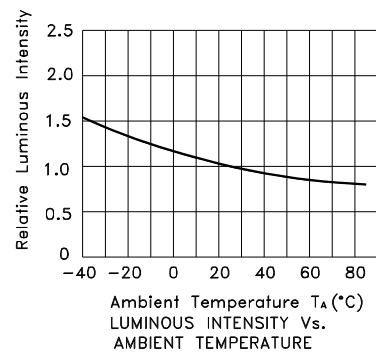
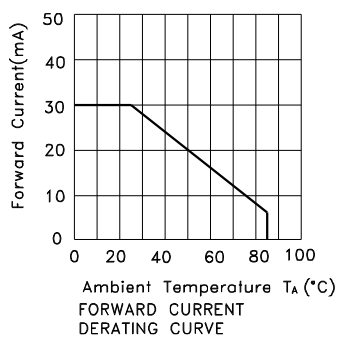
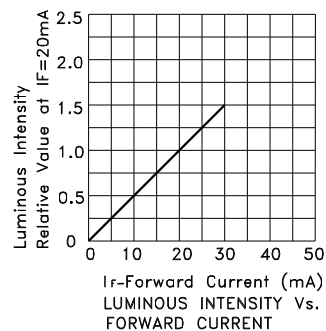
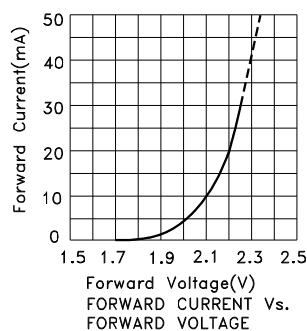
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

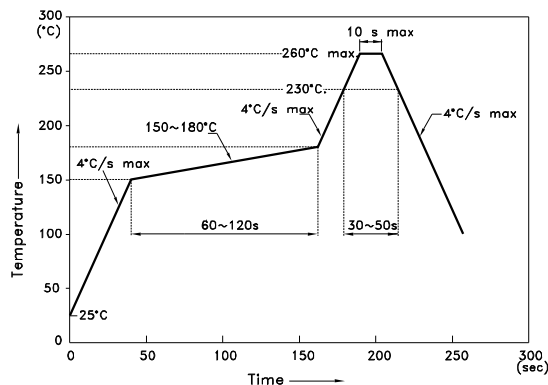
APT1608SEC/J4-PRV



APT1608SEC/J4-PRV

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

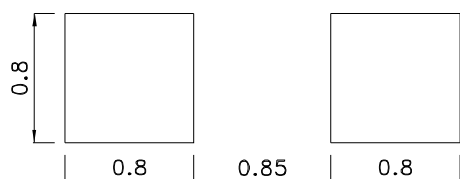
Reflow Soldering Profile For Lead-free SMT Process.



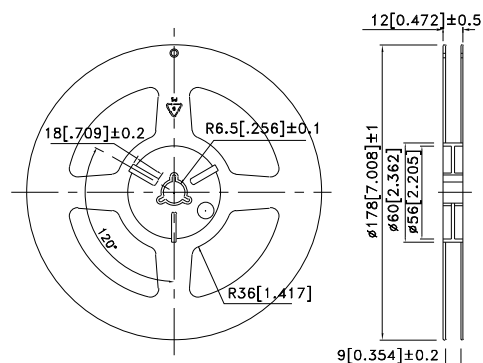
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

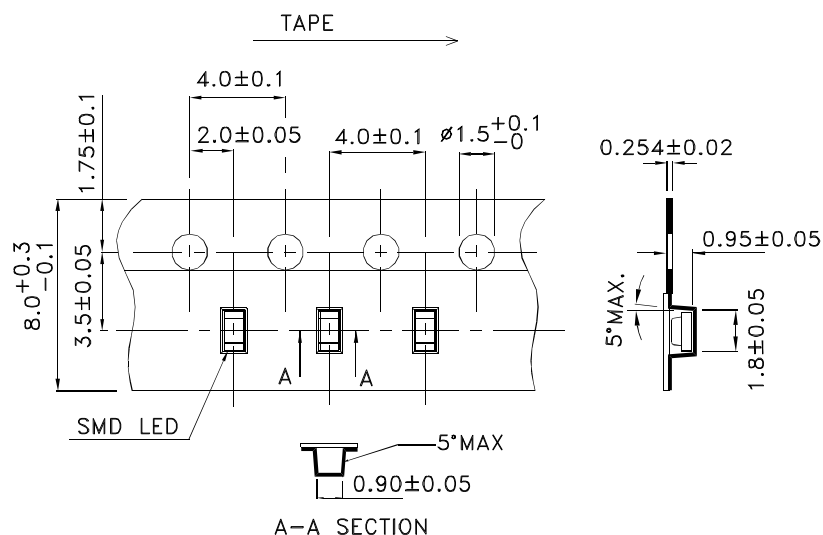
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

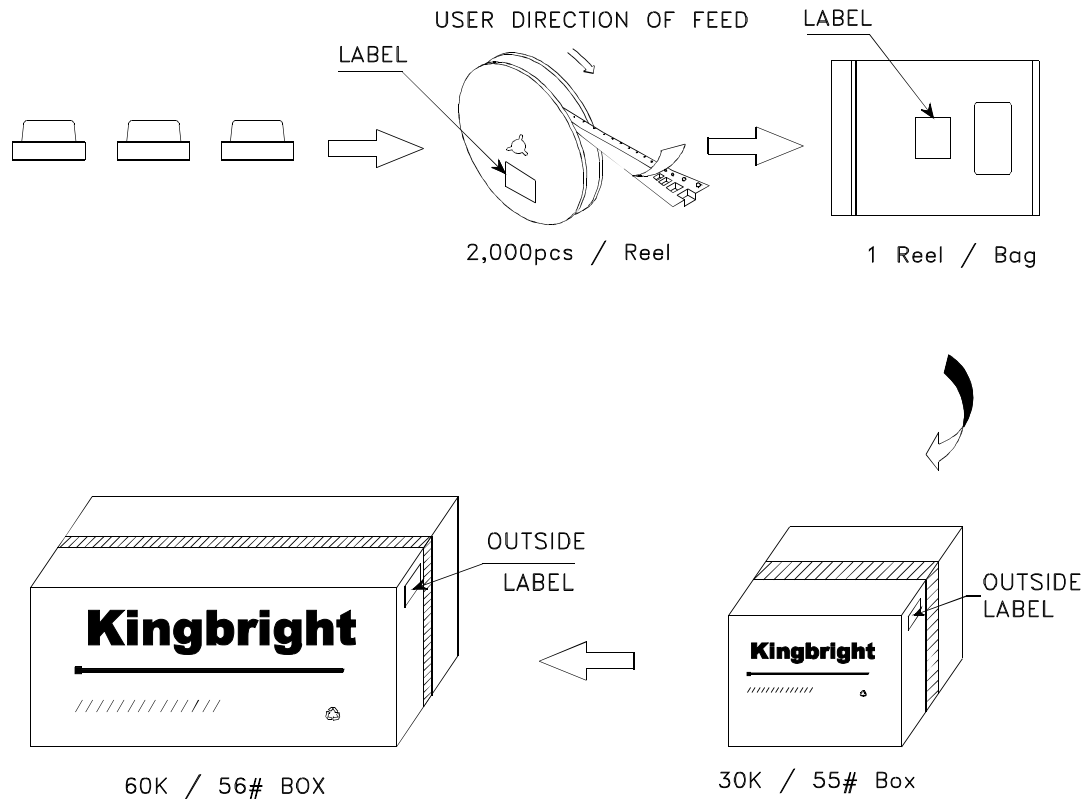



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

APT1608SEC/J4-PRV



Kingbright	
P/NO: APT1608xxx	
QTY: 2,000 pcs	Q.C. <div>Q C XX XX XXXX PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	

Part Number: APT2012SEC/J4-PRV

Super Bright Orange

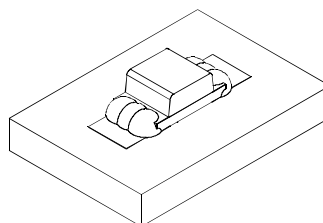
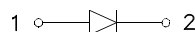
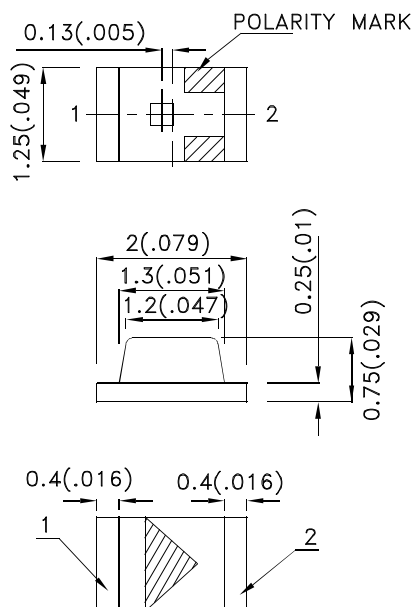
Features

- 2.0mm x1.25mm SMT LED,0.75mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APT2012SEC/J4-PRV	Super Bright Orange (AlGaInP)	Water Clear	1600	2300	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	611		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	605		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	17		nm	I _F =20mA
C	Capacitance	Super Bright Orange	27		pF	V _F =0V; f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

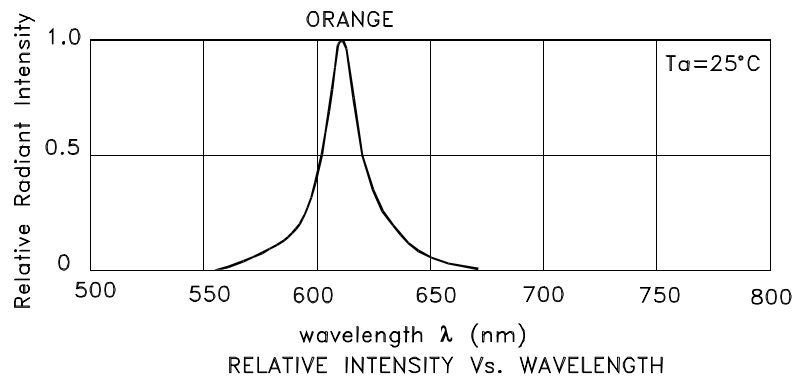
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

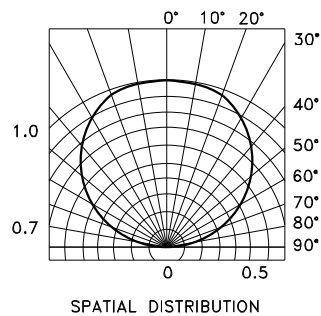
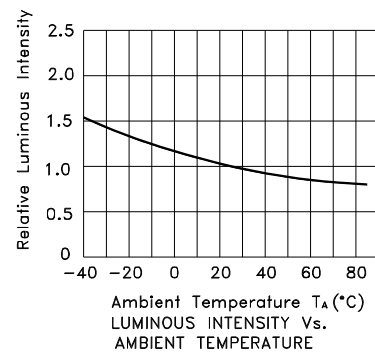
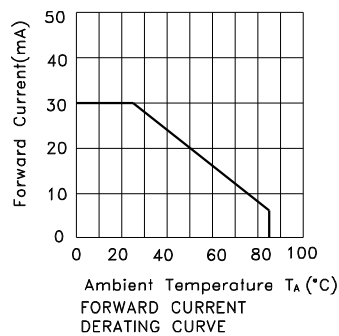
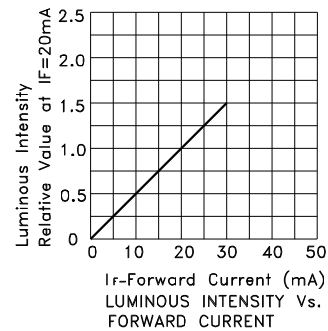
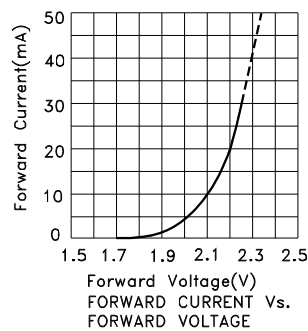
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Orange

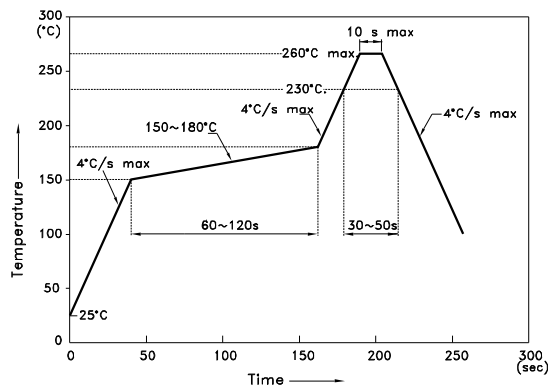
APT2012SEC/J4-PRV



APT2012SEC/J4-PRV

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



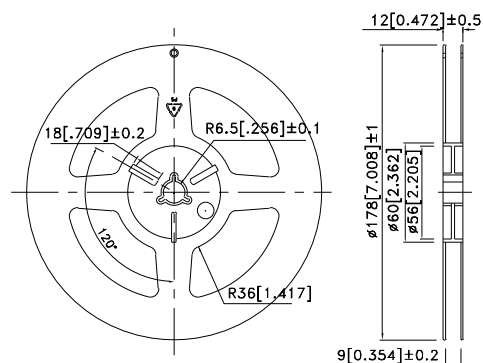
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

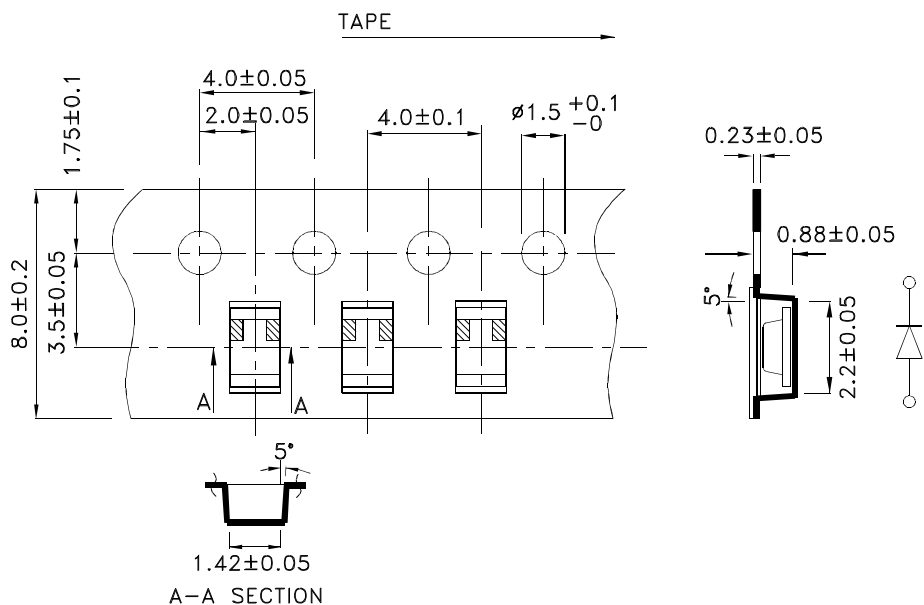
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

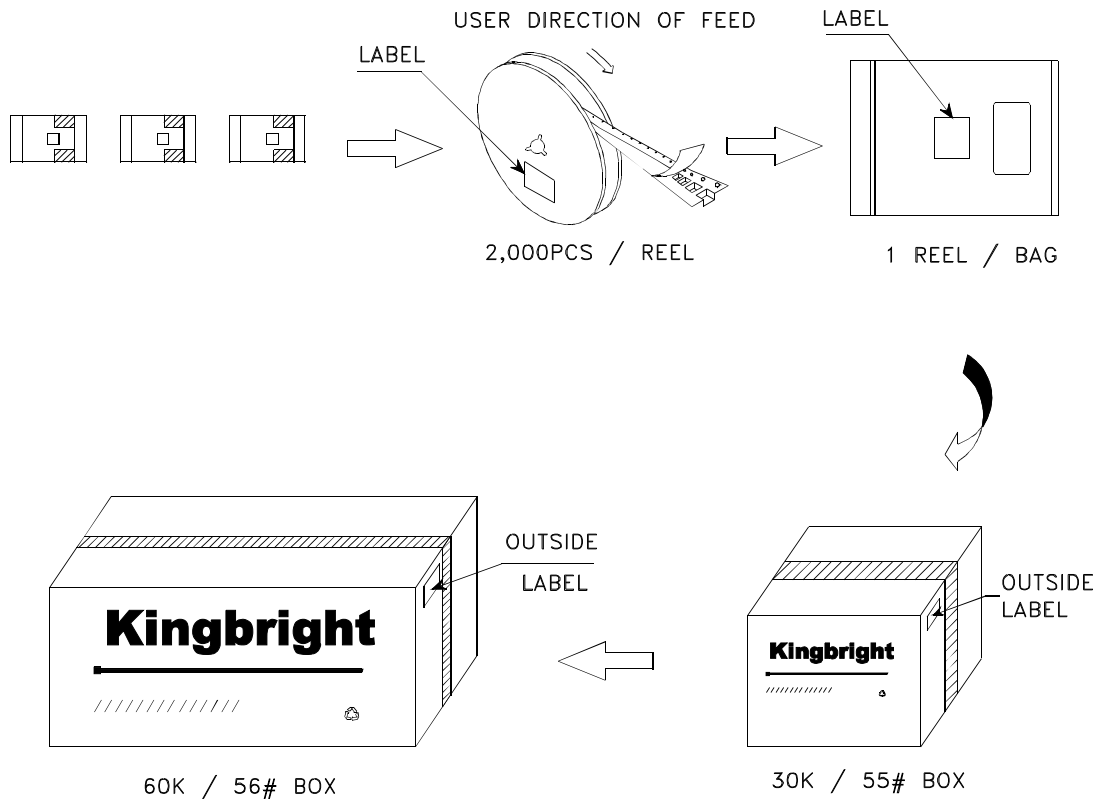



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

APT2012SEC/J4-PRV



Kingbright	
P/NO: APT2012xxx	
QTY: 2,000 pcs	Q.C.
S/N: XXXX	XX XX XXXX PASSED
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

Part Number: APT3216SEC/J4-PRV

Super Bright Orange

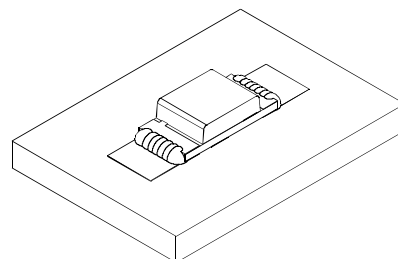
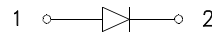
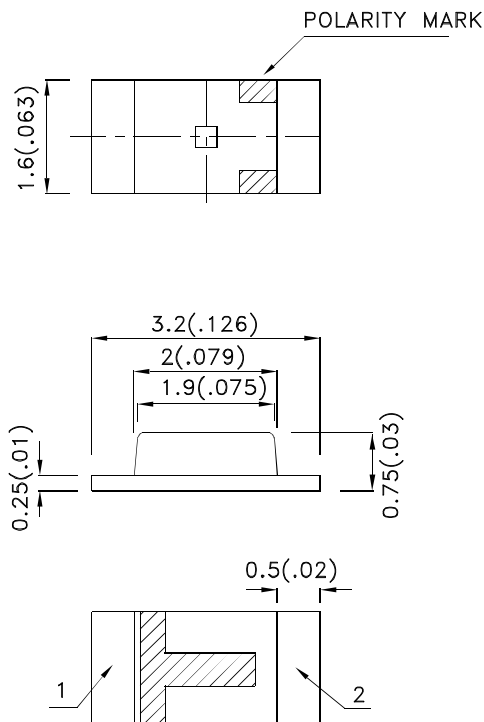
Features

- 3.2mmx1.6mm SMT LED, 0.75mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APT3216SEC/J4-PRV	Super Bright Orange (AlGaInP)	Water Clear	1600	2300	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	611		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	605		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	17		nm	I _F =20mA
C	Capacitance	Super Bright Orange	27		pF	V _F =0V; f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

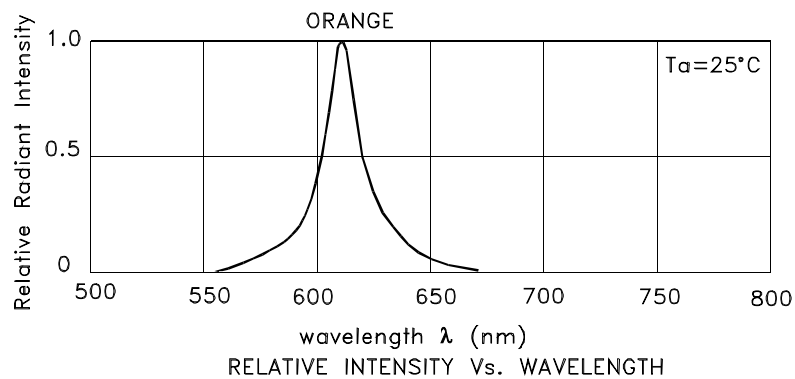
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

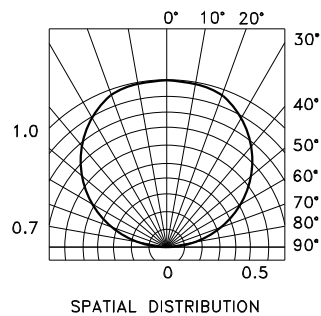
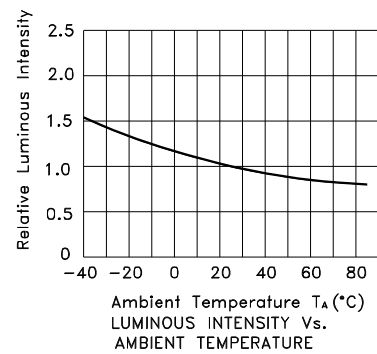
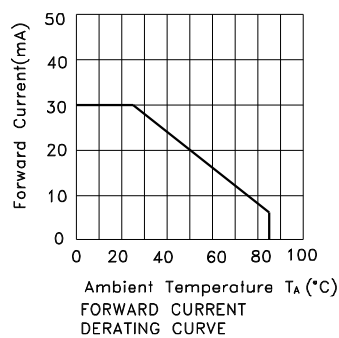
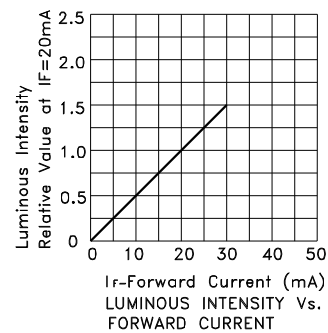
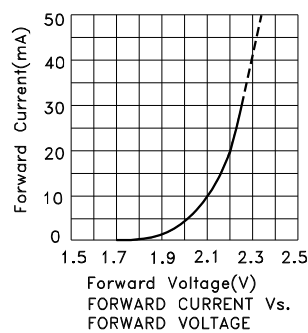
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



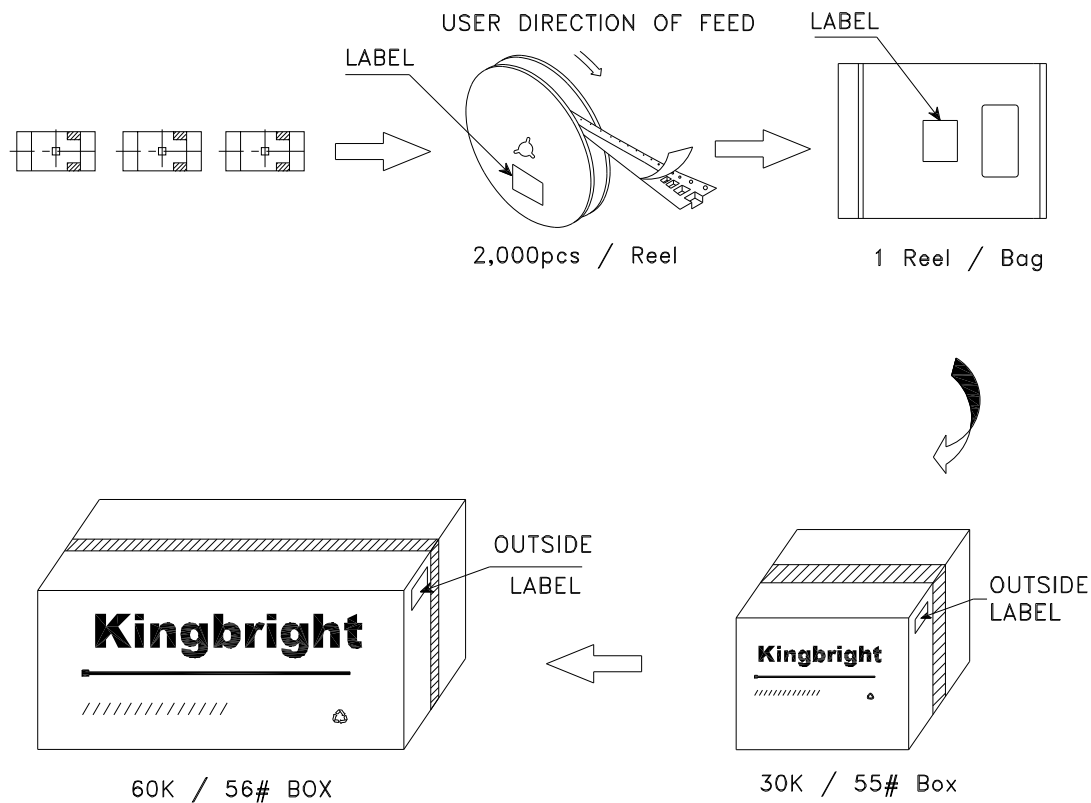
Super Bright Orange


APT3216SEC/J4-PRV



PACKING & LABEL SPECIFICATIONS

APT3216SEC/J4-PRV



Kingbright	
P/NO: APT3216xxx	
QTY: 2,000 pcs	Q.C. <div>Q C xx xx xxxx PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	

Part Number: WP710A10SEC/J4

Super Bright Orange

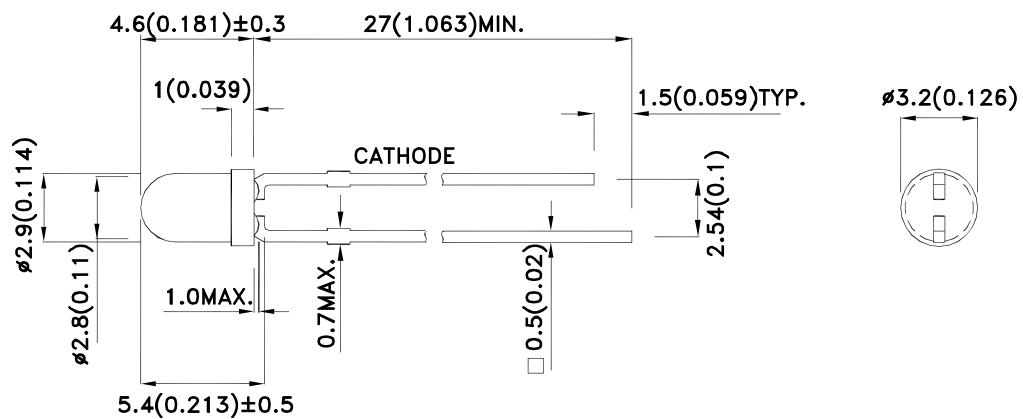
Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life - solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

The Orange source color devices are made with AlGaInP Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP710A10SEC/J4	Super Bright Orange (AlGaInP)	Water Clear	8000	10000	34°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	611		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	605		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	17		nm	IF=20mA
C	Capacitance	Super Bright Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.2	2.8	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR = 5V

Notes:

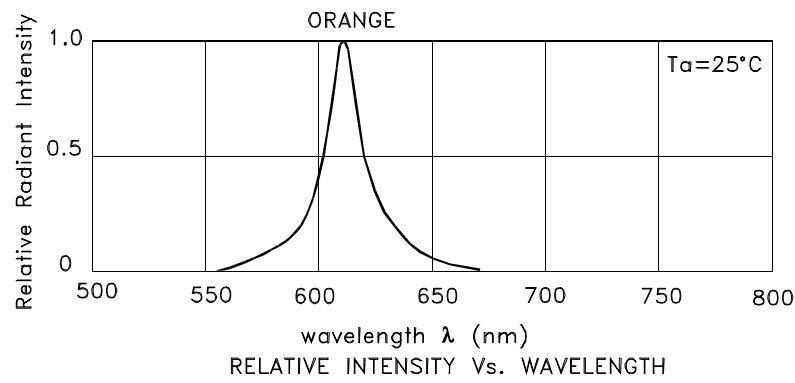
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

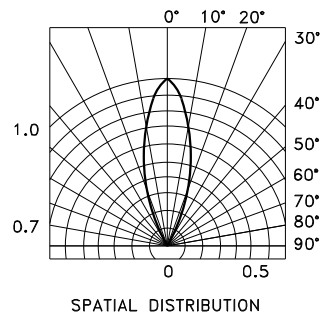
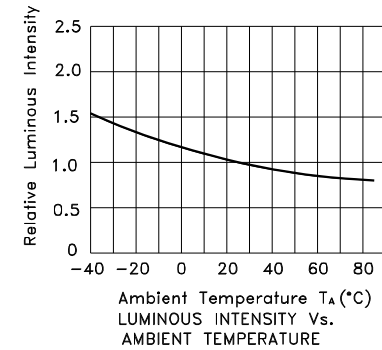
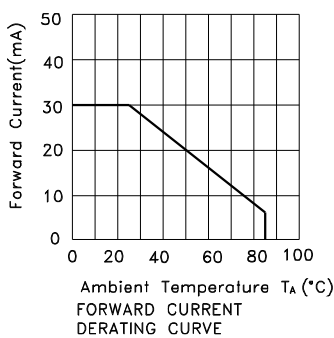
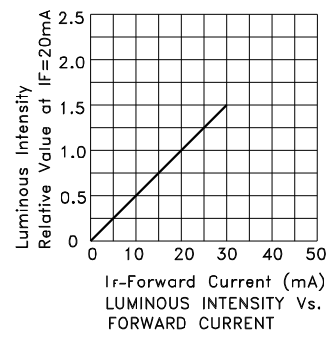
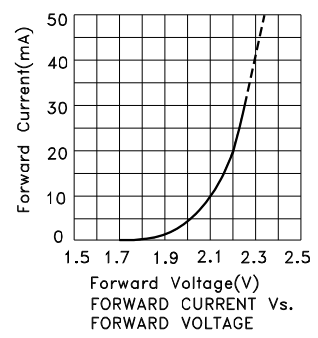
Parameter	Super Bright Orange	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.

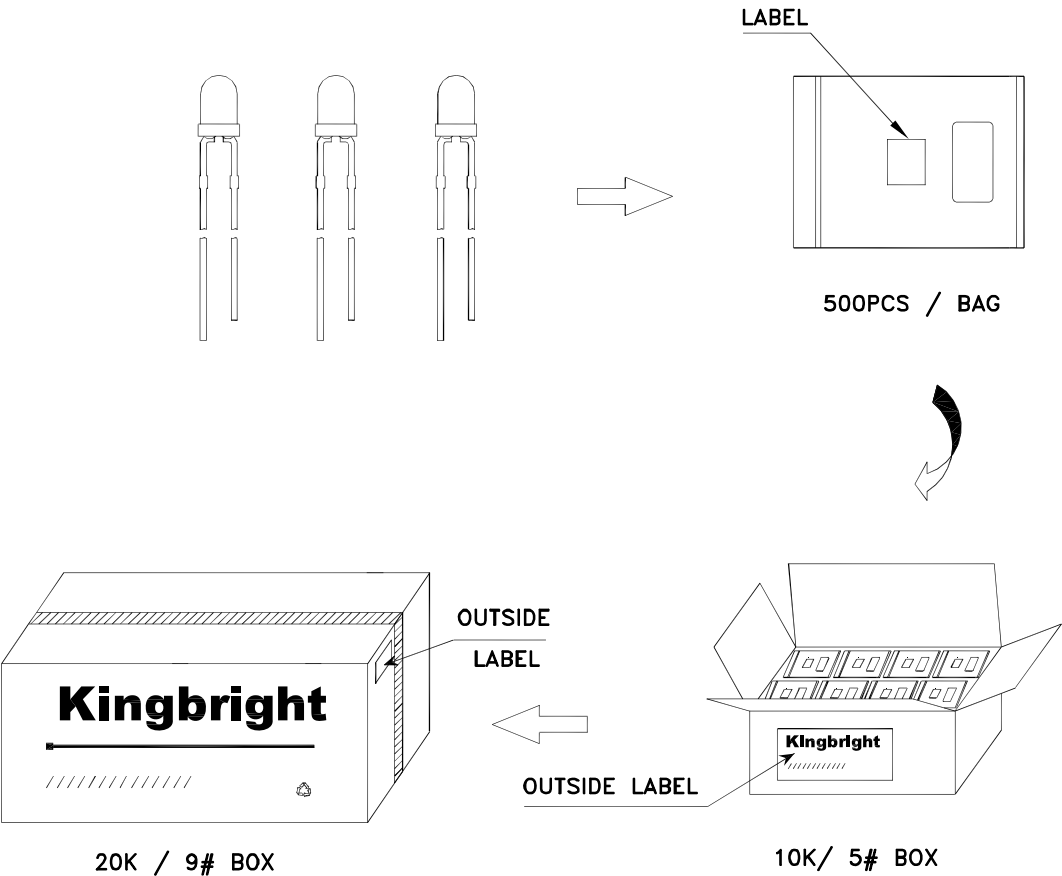



Super Bright Orange WP710A10SEC/J4



PACKING & LABEL SPECIFICATIONS

WP710A10SEC/J4



Kingbright	
P/NO: WP710A10xxx	
QTY: 500 pcs	Q.C. <div>Q C XX XX XXXX PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)

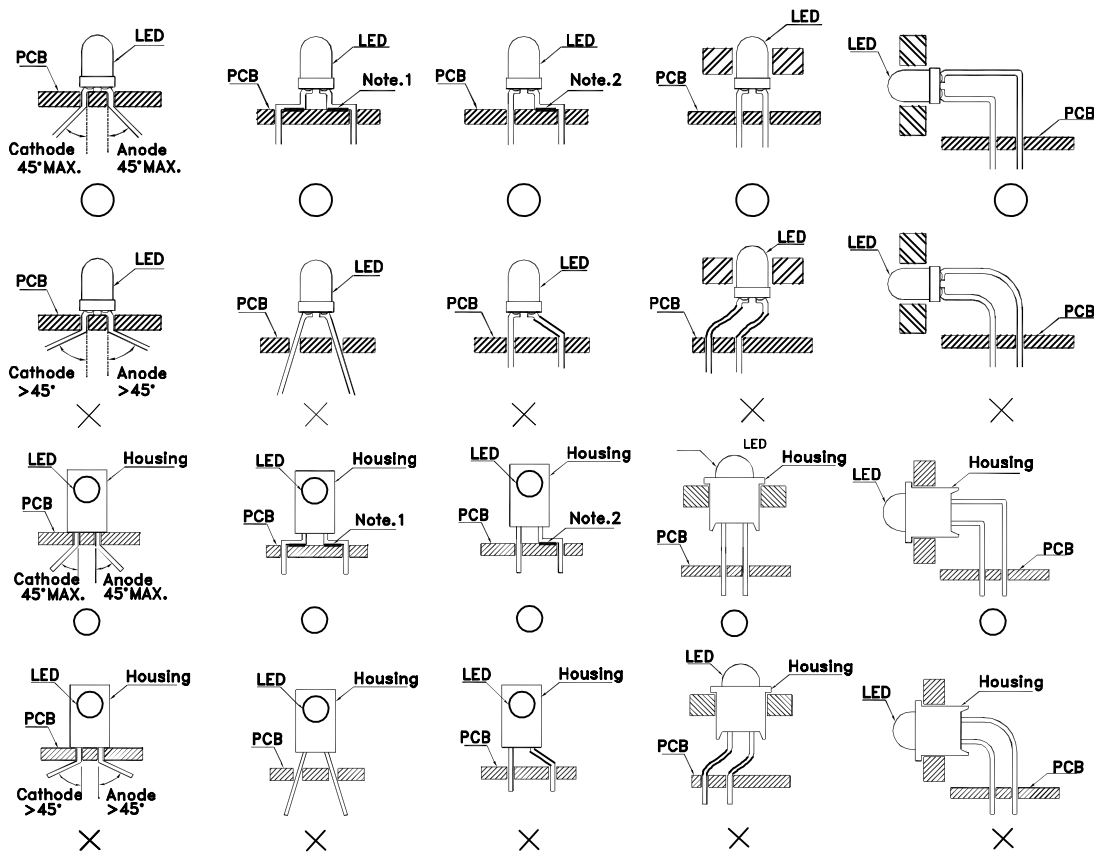


Fig.1

- “O” Correct mounting method “X” Incorrect mounting method
 Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.
2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.
- (Fig. 2)
3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

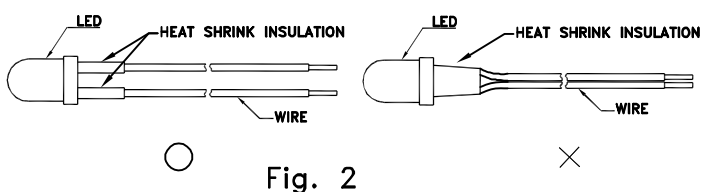


Fig. 2

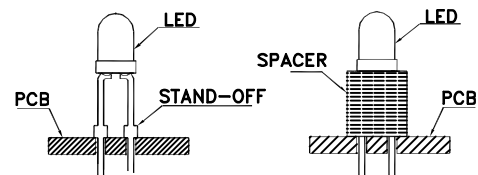


Fig. 3

Fig. 4

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)

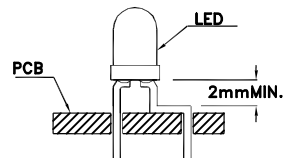


Fig. 5

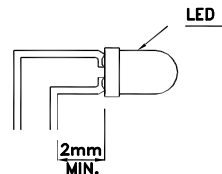


Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)
6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.

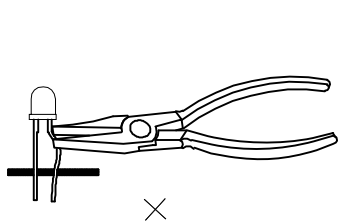


Fig. 7

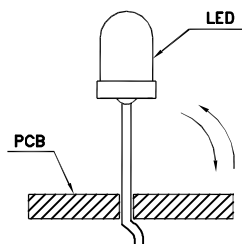


Fig. 8

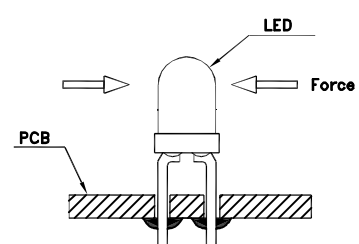
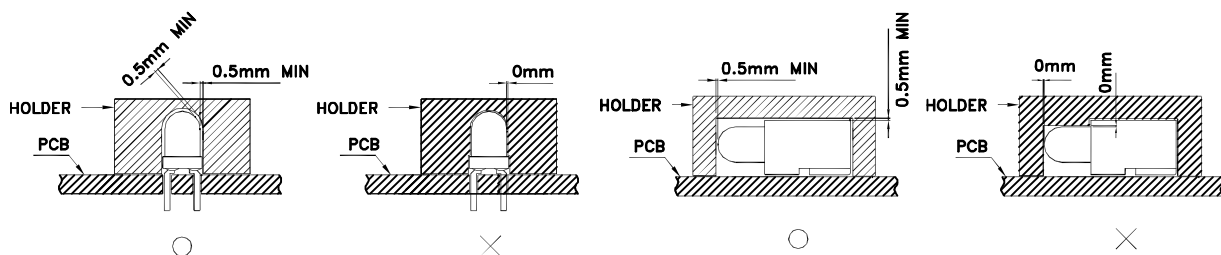


Fig. 9

7. No stress shall be applied on the LED during soldering to prevent damage.



Part Number: WP7113SEC/J4

Super Bright Orange

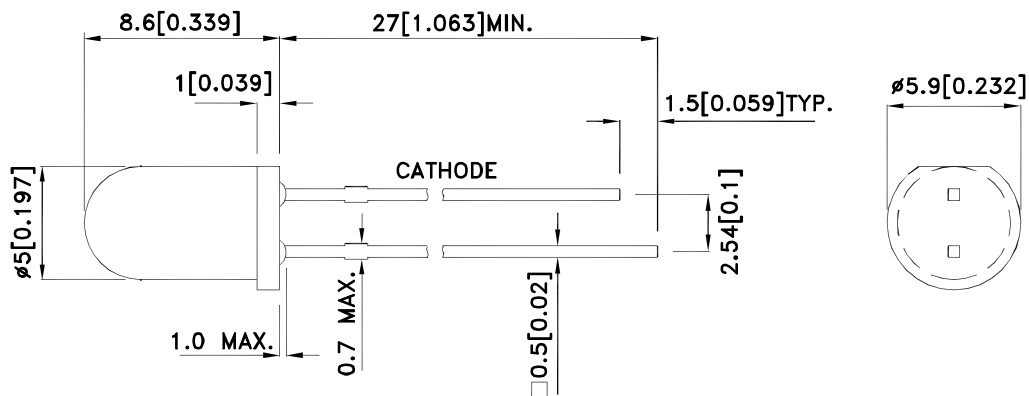
Features

- Low power consumption.
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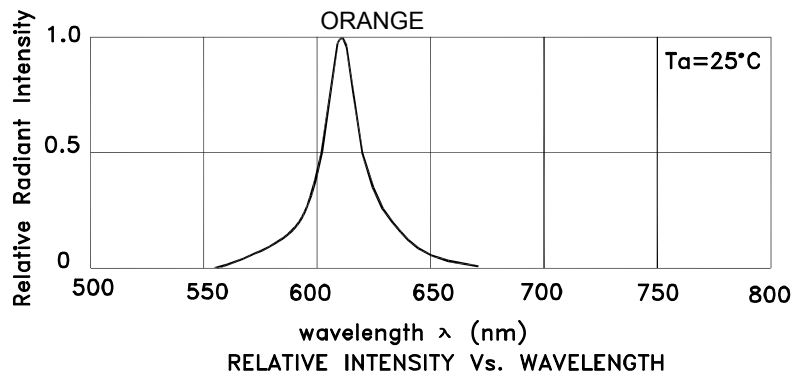
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

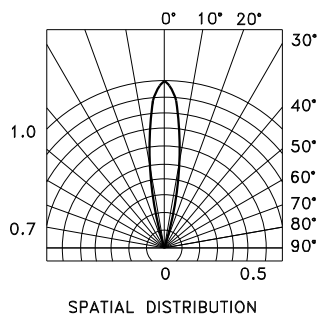
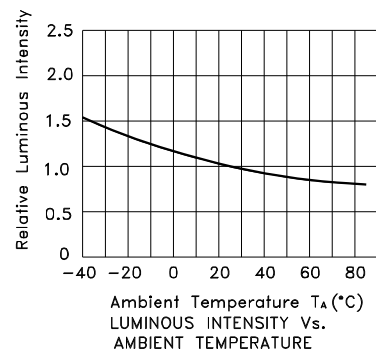
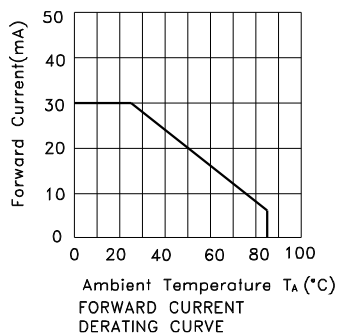
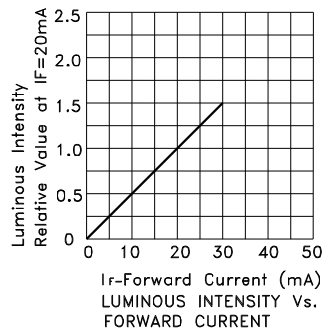
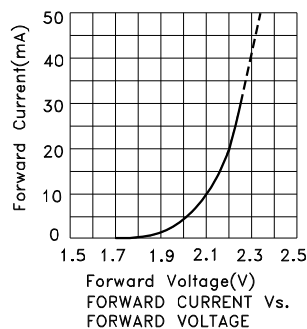
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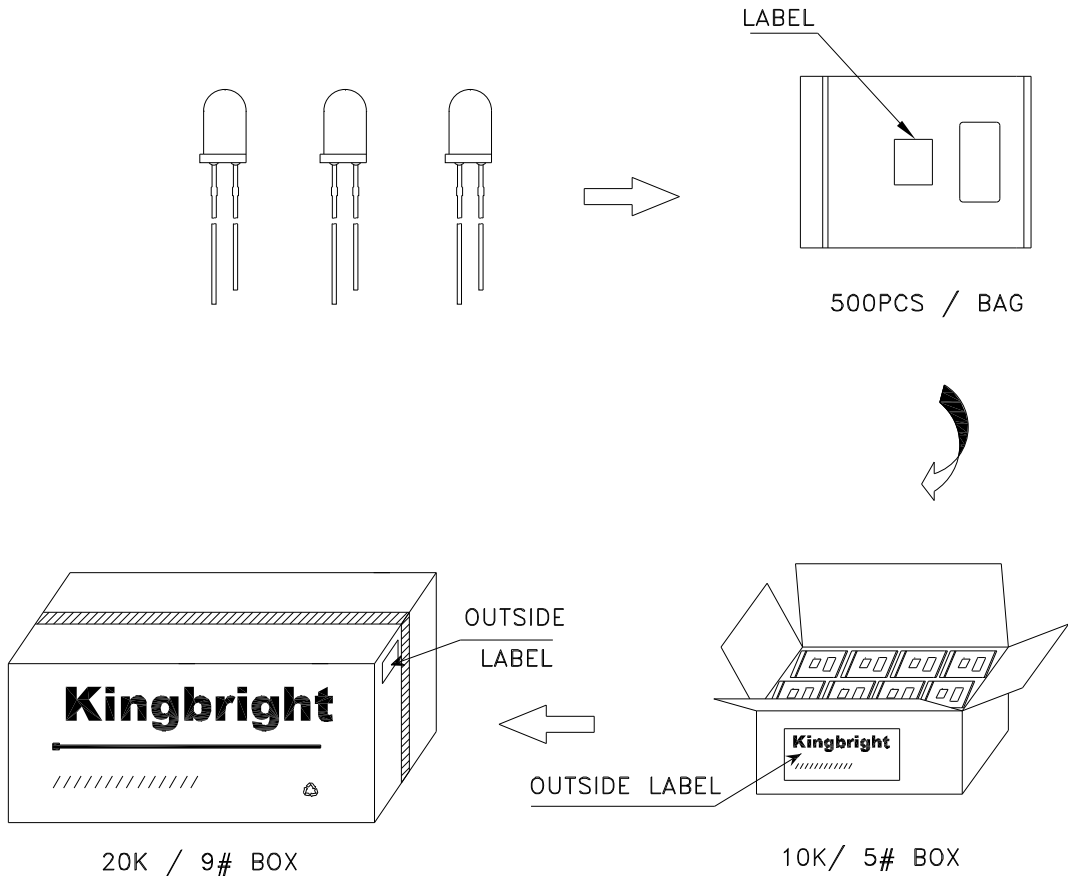



Super Bright Orange WP7113SEC/J4



PACKING & LABEL SPECIFICATIONS

WP7113SEC/J4



Kingbright		
P/NO: WP7113xxx		
QTY: 500 pcs	Q.C.	Q C
S/N: XXXX	XX XX XXXX PASSED	
CODE: XXX		
LOT NO:		
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx		
RoHS Compliant		

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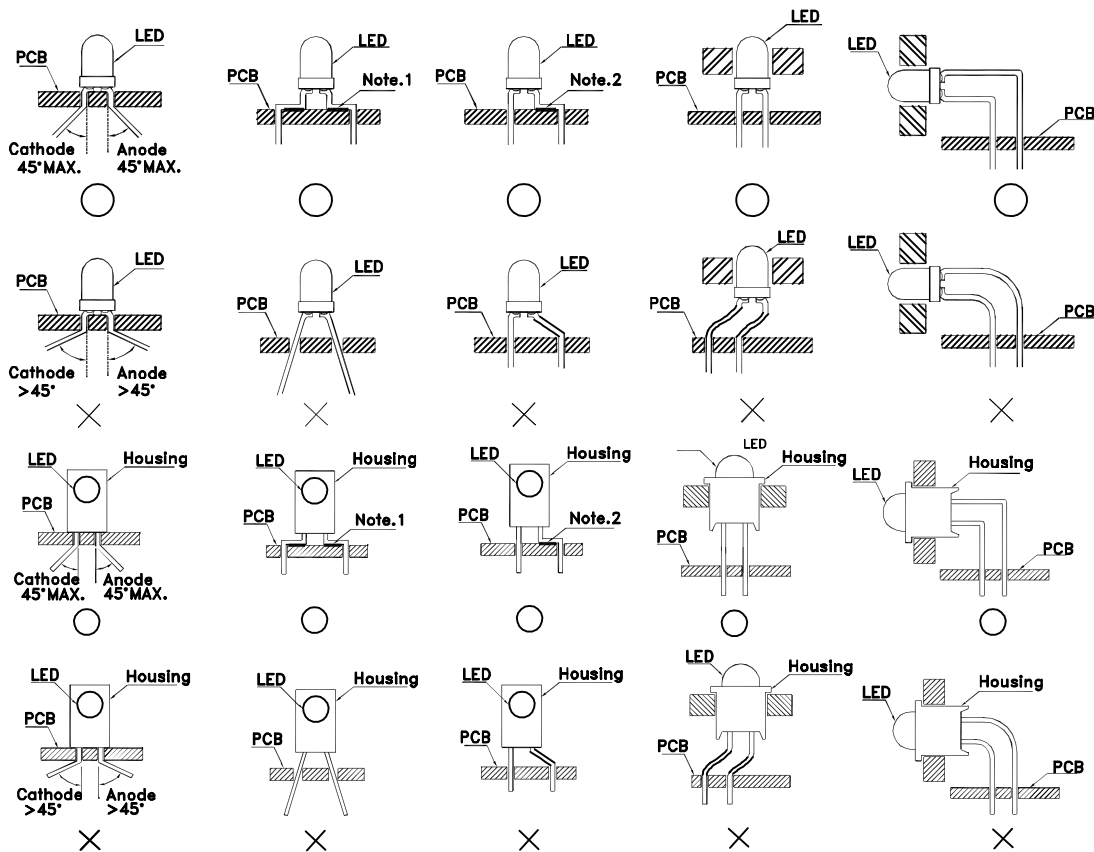


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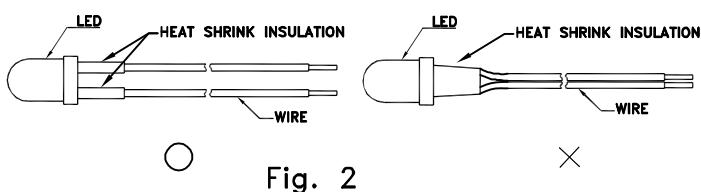


Fig. 2

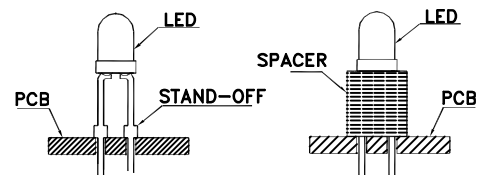


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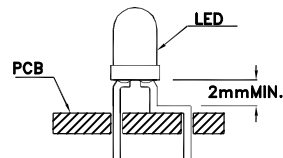


Fig. 5

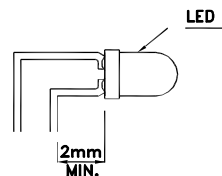


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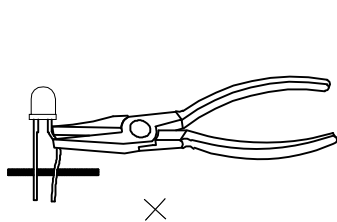


Fig. 7

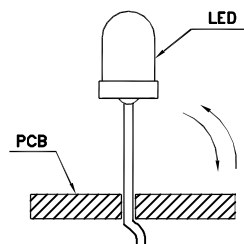


Fig. 8

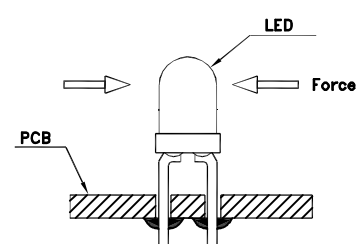


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